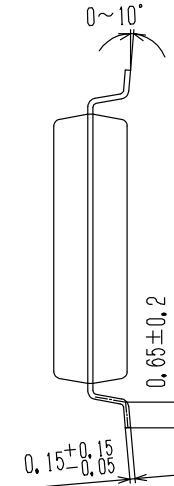
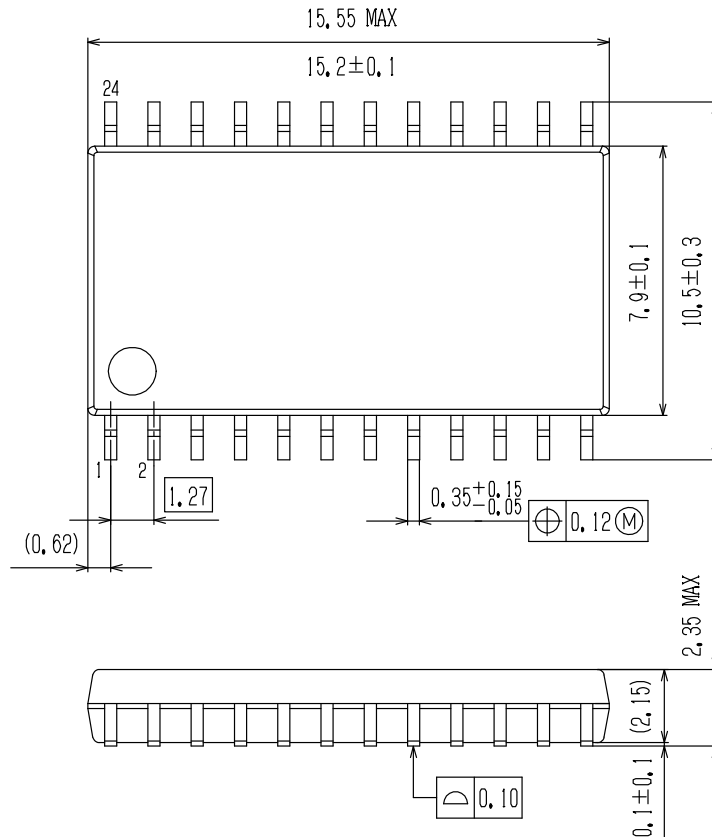
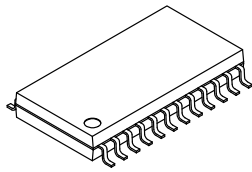
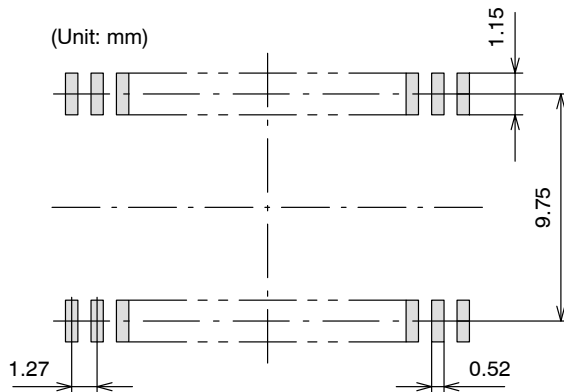


SOIC24 W / MFP24 (375 mil)
CASE 751CF
ISSUE A

DATE 08 NOV 2013



SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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| DESCRIPTION: | SOIC24 W / MFP24 (375 MIL) | PAGE 1 OF 1 |

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